

参与

2023

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名

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		MEMS						
		1 2 3 4 5 6						
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	1		ZL201010181105.3	20130213	1135038			
	2		ZL201210514737.6	20150916	1787120			
	1		ZL201010278255.6	20130320	1157236			
			ZL20091019	20120718	100514			

	3		6795.7		0			
	111		ZL201 31002 8123.1	2015 08 05	174579 6			
	2							
	SOI MEMS 1		ZL201 41019 1944.1	2016 04 06	201609 2			
		3	ZL200 81003 7306.9	2010 02 03	597434			
		2	ZL201 41016 5319.X	2016 05 25	208197 0			
	MEMS 3		ZL201 31001 2777.5	2015 09 23	179521 1			
	Semiconductor devices - Micro-electromecha nical devices - Part 25: Silicon based MEMS fabrication technology - Measurement method of pull-press and shearing strength of micro bonding area		IEC 62047 -25	2016 9 1	/			